g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-FLUKE1-DS3800HFPC**

Test Procedure for the DS3800HFPC card tested with the Fluke 9010A troubleshooter.

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release, Obsoleted several other procedures and rolled them into this one. Obsoleted: LOU-GED-DS3800NFCB-B, LOU-GED-DS3800HFPC-B, LOU-GED-DS3800HIOC-B, LOU-GED-DS3800HSCA-B, LOU-GED-DS3800HXTA-B, LOU-GED-DS3800NBIA-B, LOU-GED-DS3800DOWC-B,	R. Duvall	07/02/02
B	Page 4 Section 6.3, Chip Orientation	C. Wade	9/6/2007
C	Updated table 1 and added Section 6.5	C. Wade	4/9/2009
D	Transferred procedure from a general group to a specific single document. Also added asset numbers to section 5 and updated general format of document. Removed those parts not required for testing this card.	J. Wychulis	7/1/2010

PREPARED BY	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL
R. Duvall	J. Wychulis		Robert Duvall
DATE	**DATE**	**DATE**	**DATE**
07/02/02	7/1/2010		07/02/02

Functional test procedure for various cards tested with the Fluke 9010A

1. SCOPE

1.1 This is a functional testing procedure for various cards tested with the Fluke 9010A Troubleshooter.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
- **3.1.1 Fluke 9010 Operations manual**
- **3.1.2 Documentation for card being tested**

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
- **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection
- **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
  - **4.2.1.1** Wires broken or cracked
  - **4.2.1.2** Terminal strips / connectors broken or cracked
  - **4.2.1.3** Loose wires
  - **4.2.1.4** Components visually damaged
  - **4.2.1.5** Capacitors leaking
  - **4.2.1.6** Solder joints damaged or cold
  - **4.2.1.7** Circuit board burned or de-laminated
  - **4.2.1.8** Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 9010A Micro-system Troubleshooter connected to a PC that has a connection to the Louisville Server
1		2nd Fluke 9010A Micro-system Troubleshooter if required by test.
1		Pod as called out in next table.
1	H033521	HFPC Fixture

5.2 The following equipment is required to perform individual card tests. See table 1.

Card Tested	Test Setup	Fixture ID	Secondary Item	Additional Equipment	Primary Program	Secondary Program
DS3800HFPC	Setup 2	H033521	2nd Fluke	8088 Pod	HFPCM.S	HFPCS.S

Table 1

6. TESTING PROCESS

6.1 Setup

6.1.1 Per requirements in section 5

6.2 Testing Procedure

6.2.1 Setup equipment per figure indicated in reference table.

6.2.2 Load test program indicated in table into Fluke 9010A.

6.2.3 Apply power to UUT.

6.2.4 Execute Program 0 on Fluke.

6.2.5 Follow instructions on terminal screen.

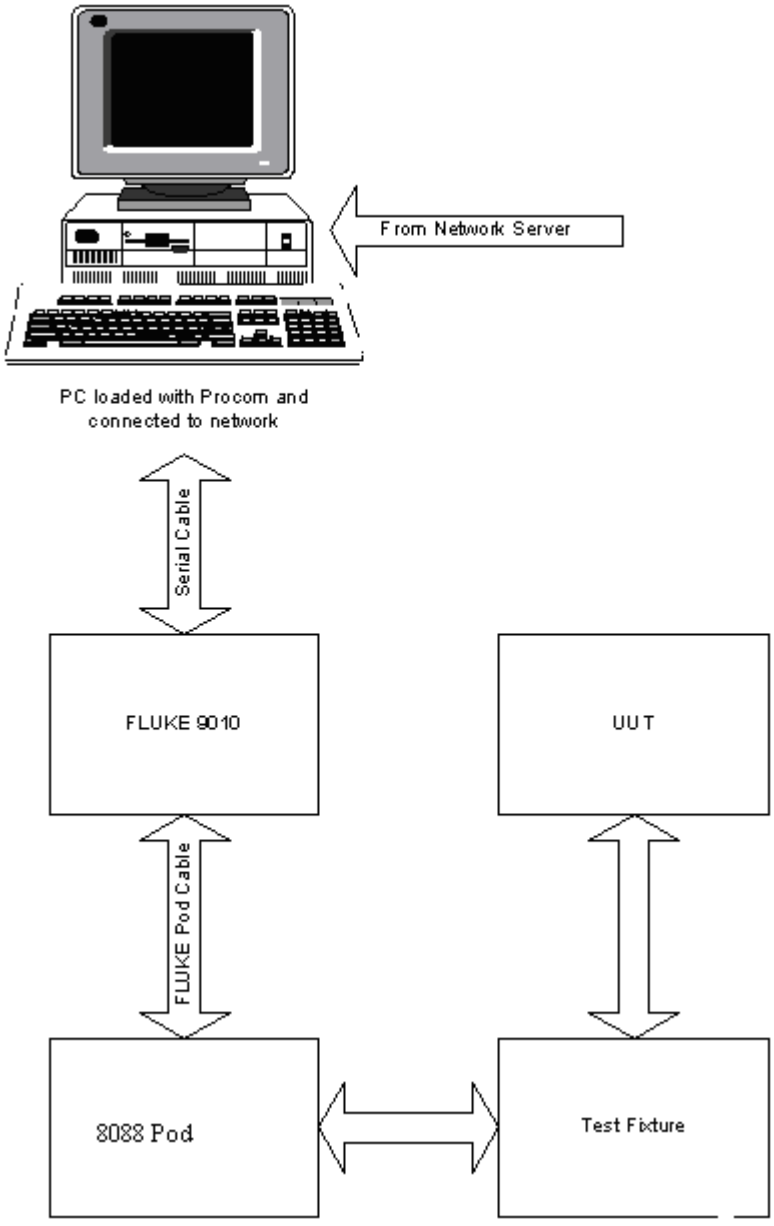
6.3 Chip Orientation

6.3.1 **SPECIAL NOTE: If firmware has to be checked outside of card and then reinstalled before sending back to customer, be sure to check orientation of all socketed chips.**

6.4 ***TEST COMPLETE unless the board is DS3800HFPB or some derivative of it.

7. NOTES

7.1 Setup



8. Attachments

8.1 None at this time.